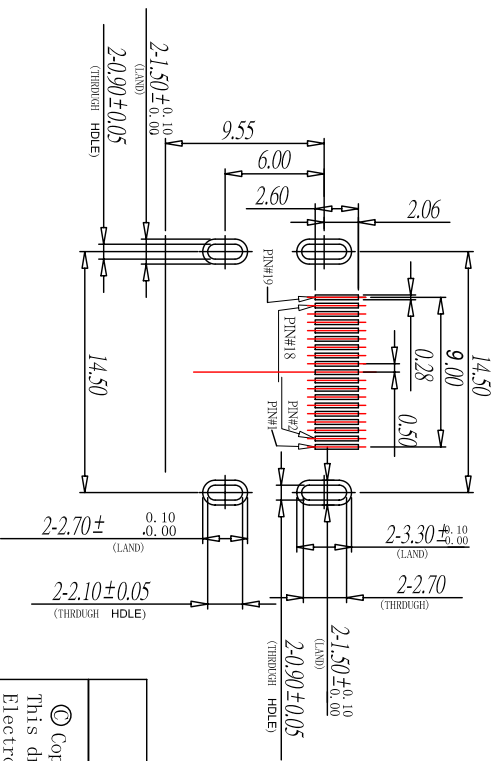
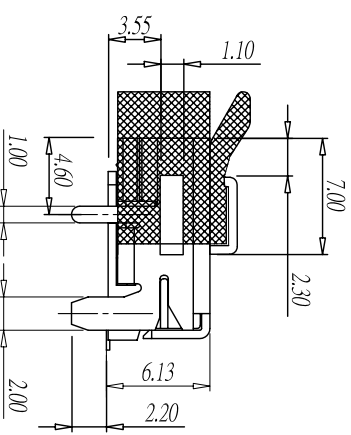
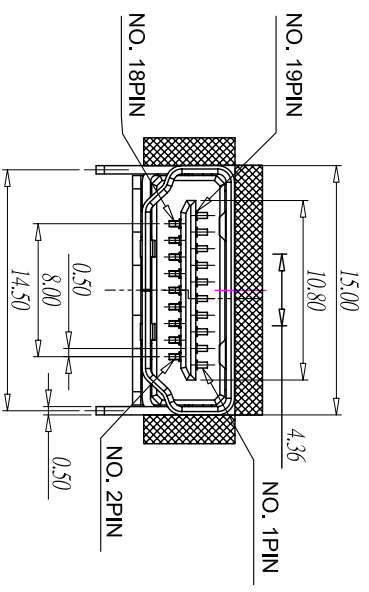
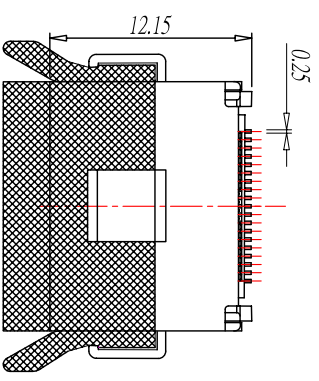


REV	ECO NO.	DATE	BY	APP'D
B	dimension updated PER ECO 002	11/8/06	KL	WEK
C	Data updated PER ECO 003	2/18/11	KL	WEK



RECOMMENDED P. C. B. LAYOUT (T=1.6 ± 0.1)

NOTE:
1. MATERIALS AND FINISH
1.1 HOUSING:
HIGH TEMP. PLASTIC, UL 94V-0 RATED.
1.2 CONTACTS:
COPPER ALLOY,
GOLD ON CONTACT AREA,
100u" MIN TIN PLATING ON SOLDER TAILS,
BOTH OVER 50u" MIN NICKEL ALL OVER.
1.3 SHIELD:
COPPER ALLOY,
PLATING NICKEL 80u" MIN ALL OVER.
2. TEMPERATURE RANGE: -25°C - +85°C
3. ELECTRICAL
3.1 CURRENT RATE: 0.5Amps
3.2 INSULATION RESISTANCE: 100Mohms
3.3 CONTACT RESISTANCE: 30mOhms
3.4 DIELECTRIC WITHSTANDING: 500V AC/min.

This component and all homogeneous subcomponents are RoHS compliant
High temp. Process Statement
Max. 80 Seconds in 225° C
and 3 Seconds in 260° C

Tolerance	.x ±0.35
.xx	±0.25

UNIT: mm

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DRAWN: KIM	DATE: 6/22/06	TITLE: HDM1 19PIN SOCKET	SIZE: B	DRAWING NO.: HDM1P-3	REV: C
CHECKED:	DATE:				
ENGINEER:	DATE:				
APPROVED:	DATE:				
APPROVED:	DATE:				
APPROVED:	DATE:				
SCALE: NONE					
				SHEET 1 OF 1	

